

CLAIMS

1. A heat spreader adapted to be insert-molded with resin on a surface of a circuit board on which a semiconductor chip is mounted so that said heat spreader covers said surface of the circuit board including an upper surface of said semiconductor chip over substantially a same area as that covered with molded resin when insert-molded with resin, said heat spreader having:

a first, main portion which defines a first gap with respect to said surface of the circuit board when insert-molded with resin; and

a second portion which defines a second gap with respect to said surface of the circuit board when insert-molded with resin, said second gap being smaller than said first gap, so that at least said second portion is embedded in said mold resin when insert-molded with resin.

2. A heat spreader as set forth in claim 1 further comprising a plurality of third portions which are in contact with said surface of the circuit board when insert-molded with resin.

3. A heat spreader as set forth in claim 2, wherein said third portions are provided on said second portions.

4. A heat spreader adapted to be insert-molded with resin on a surface of a circuit board on which a semiconductor chip is mounted so that said heat spreader covers said surface of the circuit board including an upper surface of said semiconductor chip over substantially a same area as that covered with molded resin when insert-molded with resin,

said heat spreader comprising:

a first surface positioned at a side of said circuit board and adhered with resin when insert-molded with resin; and

a second surface positioned opposite

to said first surface and at least a part thereof
defining an exposed surface when insert-molded with
resin;

said heat spreader further comprising:

5 a first part, at the first surface
thereof, defining a first gap with respect to said
surface of the circuit board when insert-molded with
resin and, at the second surface thereof, defining said
exposed surface when insert-molded with resin; and

10 a second part, at the first surface
thereof, defining a second gap with respect to said
surface of the circuit board when insert-molded with
resin, said second gap being smaller than said first gap
and, at the second surface thereof, being adhered to and
15 embedded in resin when insert-molded with resin.

5. A heat spreader as set forth in claim 4 further
comprising a plurality of third parts, at the first
surface thereof, which are in contact with said surface
of the circuit board when insert-molded with resin.

20 6. A heat spreader as set forth in claim 4,
wherein said third parts are provided on said second
part.

7. A heat spreader as set forth in claim 6 further
comprising, in a plan view thereof in parallel to said
25 surface of the circuit board when insert-molded with
resin:

a central region recessed toward said
surface of the circuit board to define a recessed portion
constituting at least a part of said second part; and

30 said recessed portion comprising a bottom
portion provided with at least one resin hole through
which resin flows when insert-molding and a peripheral
portion provided with at least one ventilation hole
through which air is ventilated when insert-molding; and

35 said recessed portion, at the second
surface thereof, being adhered to and embedded in resin
when insert-molded with resin.

8. A heat spreader as set forth in claim 3 further comprising, in a plan view thereof in parallel to said surface of the circuit board when insert-molded with resin:

5 an outer peripheral region stepped toward said surface of the circuit board to constitute at least a part of said second part along an outer periphery thereof; and

10 said outer peripheral region, at the second surface thereof, being adhered to and embedded in resin when insert-molded with resin.

15 9. A heat spreader as set forth in claim 3 further comprising, in a plan view thereof in parallel to said surface of the circuit board when insert-molded with resin:

20 a central region recessed toward said surface of the circuit board to define a recessed portion constituting at least a part of said second part, and said recessed portion comprising a bottom portion provided with at least one resin hole through which resin flows when insert-molding and a peripheral portion provided with at least one ventilation hole through which air is ventilated when insert-molding; and said recessed portion, at the second surface thereof, being adhered to and embedded in resin when insert-molded with resin;

25 an outer peripheral region stepped toward said surface of the circuit board to constitute at least a part of said second part along an outer periphery thereof; and said outer peripheral region, at the second surface thereof, being adhered to and embedded in resin when insert-molded with resin; and

30 an intermediate region between said central region and said peripheral region, at the second surface thereof, defining an exposed surface when insert-molded with resin.

35 10. A heat spreader as set forth in claim 9 further comprising, when insert-molding with resin:

means for defining a first cavity between said first surface of this heat spreader and said surface of the circuit board and means for defining a second cavity between said second surface of this heat spreader and an insert mold frame which is in contact with said first part, at the second surface thereof, and with a peripheral edge of said heat spreader; and

both said first and second cavities being filled with resin when insert molded, and a volume of said first cavity being larger than a total volume of said second cavity.

11. A semiconductor device comprising:

a circuit board having a surface;
a semiconductor chip mounted on said surface of the circuit board; and
a heat spreader having a first, main portion which defines a first gap to said surface of the circuit board, and a second portion which defines a second gap to said surface of the circuit board, said second gap being smaller than said first gap; and
a resin insert-molded with said heat spreader integrally on said surface of the circuit board so as to cover an area of said surface including an upper surface of said semiconductor chip, so that at least said second portion is embedded in said resin.

12. A semiconductor device as set forth in claim 11, wherein said heat spreader further comprises a plurality of third portions which are in contact with said surface of the circuit board.

13. A semiconductor device as set forth in claim 12, wherein said third portions are provided on said second portions.

14. A semiconductor device comprising:

a circuit board having a surface;
a semiconductor chip mounted on said surface of the circuit board; and
a heat spreader insert-molded with resin

on a surface of a circuit board so that said heat spreader covers said surface of the circuit board including an upper surface of said semiconductor chip over substantially a same area as that covered with
5 molded resin;

said heat spreader comprising:

a first surface positioned at a side of said circuit board and adhered with resin; and

a second surface positioned opposite
10 to said first surface and at least a part thereof defining an exposed surface;

said heat spreader further comprising:

a first part, at the first surface thereof, defining a first gap with respect to said
15 surface of the circuit board and, at the second surface thereof, defining said exposed surface; and

a second part, at the first surface thereof, defining a second gap with respect to said surface of the circuit board, said second gap being
20 smaller than said first gap and, at the second surface thereof, being adhered to and embedded in resin; and

said resin insert-molded with said heat spreader integrally on said surface of the circuit board so as to cover an area of said surface including an
25 upper surface of said semiconductor chip, so that said second part of the heat spreader, at the first surface thereof, is adhered to and embedded in said resin.

15. A semiconductor device as set forth in claim 14, wherein said heat spreader further comprises a
30 plurality of third parts, at the first surface thereof, which are in contact with said surface of the circuit board.

16. A semiconductor device as set forth in claim 14, wherein said third parts are provided on said second
35 part.

17. A semiconductor device as set forth in claim 14, wherein said heat spreader further comprises, in a

plan view thereof in parallel to said surface of the circuit board:

5 a central region recessed toward said surface of the circuit board to define a recessed portion constituting at least a part of said second part; and

said recessed portion comprising a bottom portion provided with at least one resin hole through which resin flows when insert-molding and a peripheral portion provided with at least one ventilation hole through which air is ventilated when insert-molding; and

10 said recessed portion, at the second surface thereof, being adhered to and embedded in resin.

18. A semiconductor device as set forth in claim 14, wherein said heat spreader further comprises, in a plan view thereof in parallel to said surface of the circuit board:

20 an outer peripheral region stepped toward said surface of the circuit board to constitutes at least a part of said second part along an outer periphery of the heat spreader; and

said outer peripheral region, at the second surface thereof, being adhered to and embedded in resin.

19. A semiconductor device as set forth in claim 14, wherein said heat spreader further comprises, in a plan view thereof in parallel to said surface of the circuit board:

30 a central region recessed toward said surface of the circuit board to define a recessed portion constituting at least a part of said second part, and said recessed portion comprising a bottom portion provided with at least one resin hole through which resin flows when insert-molding and a peripheral portion provided with at least one ventilation hole through which air is ventilated when insert-molding; and said recessed portion, at the second surface thereof, being adhered to and embedded in resin;

an outer peripheral region stepped toward said surface of the circuit board to constitute at least a part of said second part along an outer periphery of the heat spreader; and said outer peripheral region, at the second surface thereof, being adhered to and embedded in resin; and

an intermediate region between said central region and said peripheral region, at the second surface thereof, defining an exposed surface.

20. A semiconductor device as set forth in claim 14, wherein said heat spreader further comprises, when insert-molding with resin:

means for defining a first cavity between said first surface of this heat spreader and said surface of the circuit and means for defining a second cavity between said second surface of this heat spreader and an insert mold frame which is in contact with said first part, at the second surface thereof, and with a peripheral edge of said heat spreader; and

both said first and second spaces being filled with resin, and a volume of said first cavity is larger than a total volume of said second cavity.

21. A method for manufacturing a semiconductor device; said device comprising a semiconductor chip mounted on said surface of the circuit board; and a heat spreader insert-molded with resin on a surface of a circuit board so that said heat spreader covers said surface of the circuit board including an upper surface of said semiconductor chip over substantially a same area as that covered with molded resin, said heat spreader comprising: a first surface positioned at a side of said circuit board and adhered with resin; and a second surface positioned opposite to said first surface and at least a part thereof defining an exposed surface; and said heat spreader further comprising: a first part, at the first surface thereof, defining a first gap with respect to said surface of the circuit board and, at the

second surface thereof, defining said exposed surface;
and a second part, at the first surface thereof, defining
a second gap with respect to said surface of the circuit
board, said second gap being smaller than said first gap
and, at the second surface thereof, being adhered to and
embedded in resin:

said method comprising:

setting a molding component to define a
mold cavity comprising a first cavity between said first
surface of this heat spreader and said surface of the
circuit board and a second cavity between said second
surface of this heat spreader and said components, so
that at least a part of said molding components is in
contact with said first part, at the second surface
thereof, and at least a remaining part of said molding
component is in contact with a peripheral edge of said
heat spreader; and

injecting resin simultaneously into both
said first and second cavities so that both said first
and second cavities are filled with resin.

22. A method as set forth in claim 21, wherein
resin injected into said first and second cavities from a
gate which is arranged at a peripheral position of said
heat spreader, so that a flow of resin into said first
cavity is larger in quantity than that into said second
cavity.

23. A method as set forth in claim 22, wherein a
relatively larger amount of resin flows into said first
cavity and then a part thereof flows into a central
region of the second cavity through a resin hole, and a
relatively smaller amount of resin flows into peripheral
region of the second cavity along a periphery of the heat
spreader toward an opposite side thereof from one side
thereof near said gate.